



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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## Features

- $BV_{CEO} > -40V$
- Small Form Factor Thermally Efficient Package. Enables Higher Density End Products
- $I_C = -2A$  Continuous Collector Current
- $I_{CM} = -3A$  Peak Pulse Current
- Low Saturation Voltage  $V_{CE(sat)} < -320mV @ -1A$
- Complementary NPN Type: NK-DXTN22040DFGQ
- Rated to  $+175^{\circ}C$  – Ideal For High Temperature Environment
- Wettable Flank For Improved Optical Inspection

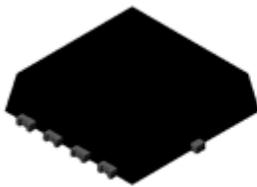
## Mechanical Data

- Case: PowerDI<sup>®</sup> 3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.03 grams (Approximate)

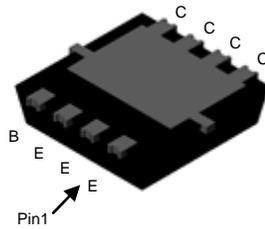
## Applications

- High-Side Switch
- Supply Line Switching
- Motor Driving

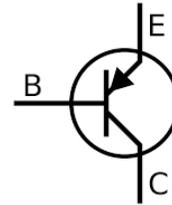
PowerDI3333-8 (SWP) (Type UX)



Top View



Bottom View



Device Symbol

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-40	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-2	A
Peak Pulse Collector Current	I <sub>CM</sub>	-3	
Continuous Base Current	I <sub>B</sub>	-100	mA
Peak Pulse Base Current	I <sub>BM</sub>	-200	

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

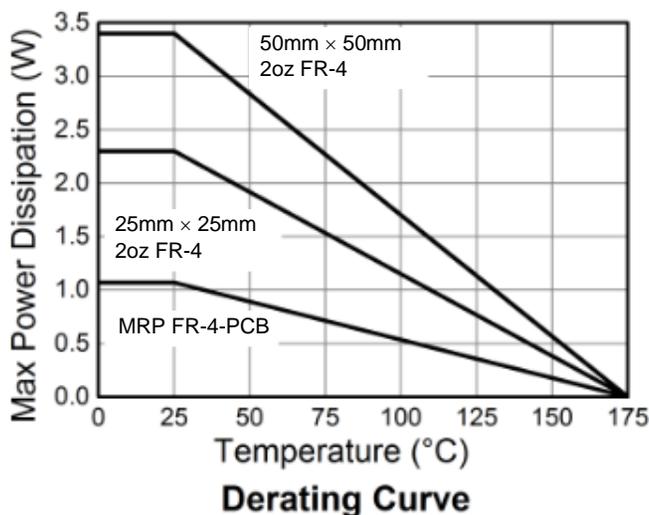
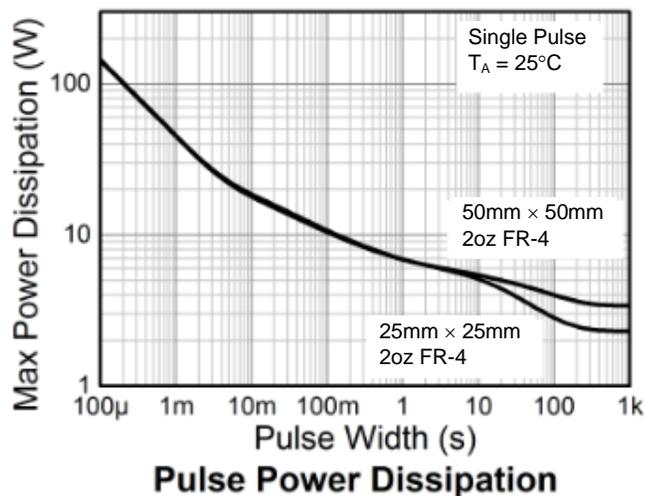
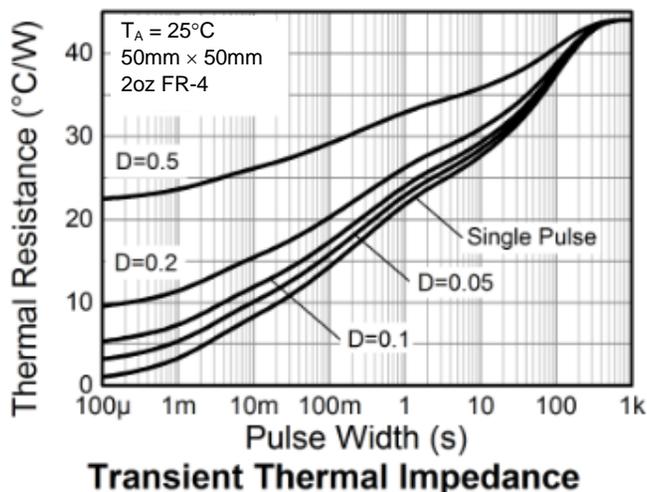
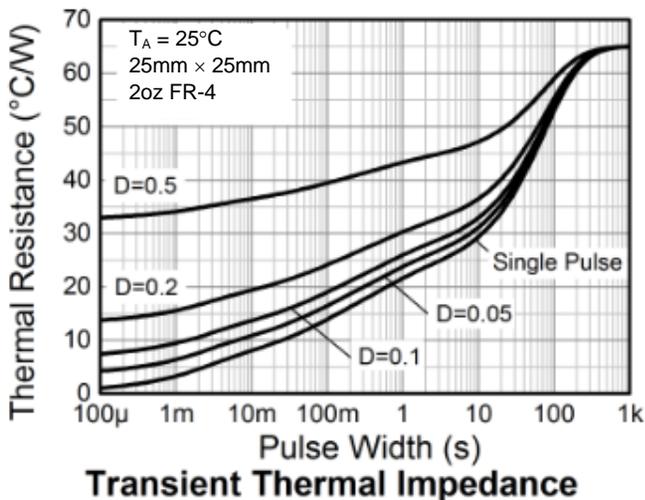
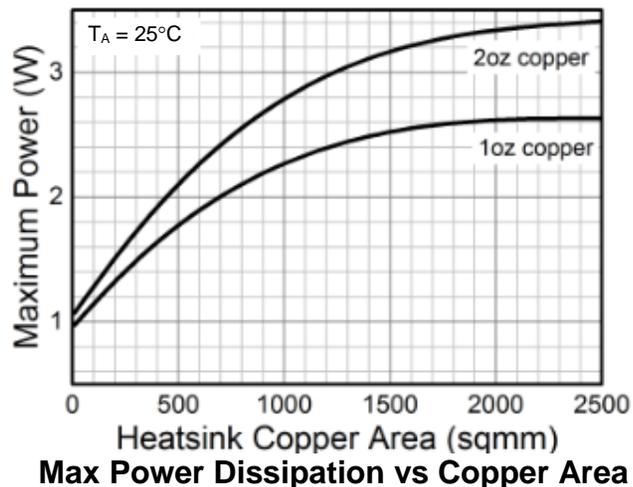
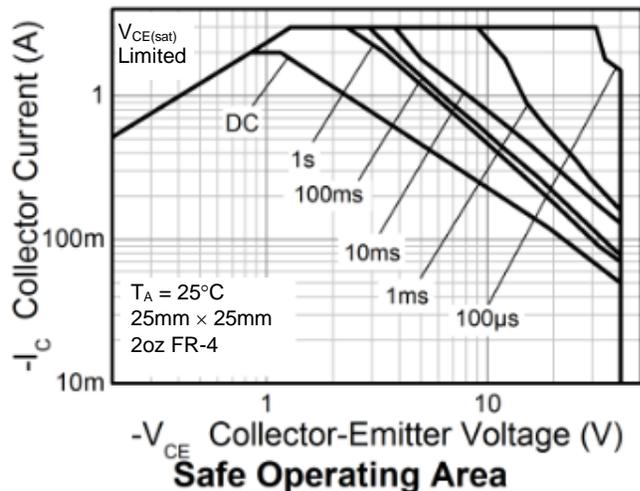
Characteristic	Symbol	Value	Unit	
Power Dissipation	P <sub>D</sub>	(Note 5)	1.07	W
		(Note 6)	2.3	W
		(Note 7)	3.4	W
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	(Note 5)	140	°C/W
		(Note 6)	65	°C/W
		(Note 7)	44	°C/W
Thermal Resistance, Junction to Leads (Note 8)	R <sub>θJL</sub>	11	°C/W	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C	

**ESD Ratings** (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge – Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge – Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the collector tab on MRP FR4-PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as Note 5, except the device is mounted on 25mm × 25mm 2oz copper.
  7. Same as Note 5, except the device is mounted on 50mm × 50mm 2oz copper.
  8. Thermal resistance from junction to solder-point (at the collector tab).
  9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

**Thermal Characteristics and Derating Information**

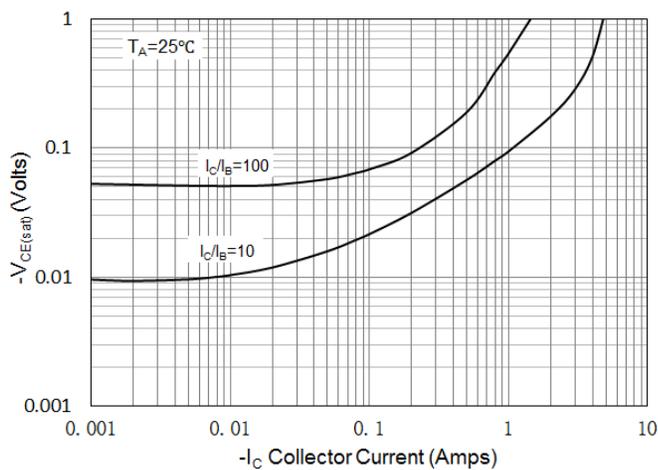


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

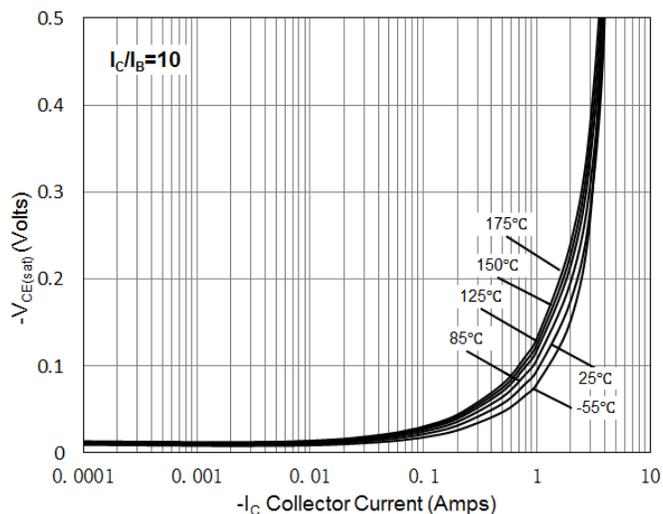
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-50	-71	—	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	-40	-58	—	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.5	—	V	I <sub>E</sub> = -100μA
Collector-Base Cut-Off Current	I <sub>CBO</sub>	—	-1 -0.1	-0.1 -20	μA	V <sub>CB</sub> = -50V V <sub>CB</sub> = -50V, T <sub>A</sub> = +150°C
Emitter-Base Cut-Off Current	I <sub>EBO</sub>	—	-1	-20	nA	V <sub>EB</sub> = -6V
Collector-Emitter Cut-Off Current	I <sub>CES</sub>	—	-1	-20	nA	V <sub>CE</sub> = -40V, V <sub>BE</sub> = 0V
Static Forward Current Transfer Ratio (Note 10)	h <sub>FE</sub>	340 300 200 120	410 354 303 203	— 900 — —	—	I <sub>C</sub> = -100mA, V <sub>CE</sub> = -2V I <sub>C</sub> = -500mA, V <sub>CE</sub> = -2V I <sub>C</sub> = -1A, V <sub>CE</sub> = -2V I <sub>C</sub> = -2A, V <sub>CE</sub> = -2V
Collector-Emitter Saturation Voltage (Note 10)	V <sub>CE(sat)</sub>	—	-56 -48 -81 -146 -218	-140 -170 -320 -400 -600	mV	I <sub>C</sub> = -100mA, I <sub>B</sub> = -1mA I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA I <sub>C</sub> = -2A, I <sub>B</sub> = -200mA I <sub>C</sub> = -3A, I <sub>B</sub> = -300mA
Collector-Emitter Saturation Resistance (Note 10)	R <sub>CE(sat)</sub>	—	—	320	mΩ	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
Base-Emitter Saturation Voltage (Note 10)	V <sub>BE(sat)</sub>	—	-0.88	-1	V	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
Base-Emitter Turn-On Voltage (Note 10)	V <sub>BE(on)</sub>	—	-0.76	-0.9	V	I <sub>C</sub> = -1A, V <sub>CE</sub> = -2V
Transition Frequency	f <sub>T</sub>	—	120	—	MHz	I <sub>C</sub> = -50mA, V <sub>CE</sub> = -10V f = 100MHz
Output Capacitance	C <sub>obo</sub>	—	12	—	pF	V <sub>CB</sub> = -10V, f = 1MHz
Switching Characteristics	t <sub>delay</sub>	—	10	—	ns	V <sub>CC</sub> = -10V, I <sub>C</sub> = -500mA I <sub>B1</sub> = -I <sub>B2</sub> = -50mA
	t <sub>rise</sub>	—	144	—	ns	
	t <sub>storage</sub>	—	704	—	ns	
	t <sub>fall</sub>	—	48.5	—	ns	

Note: 10. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

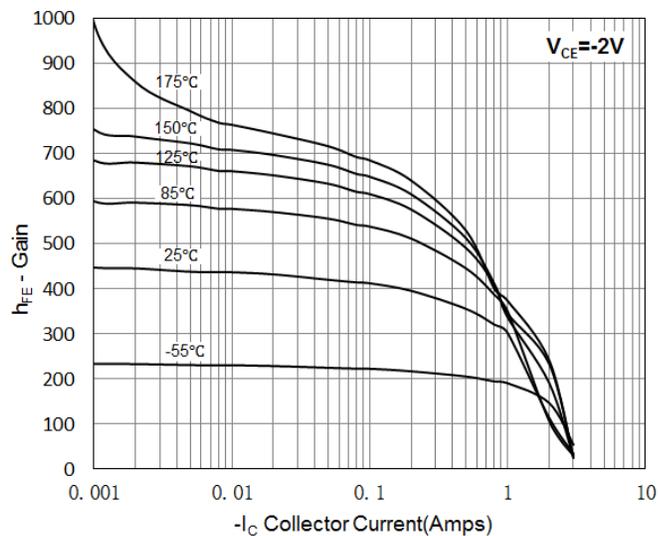
**Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



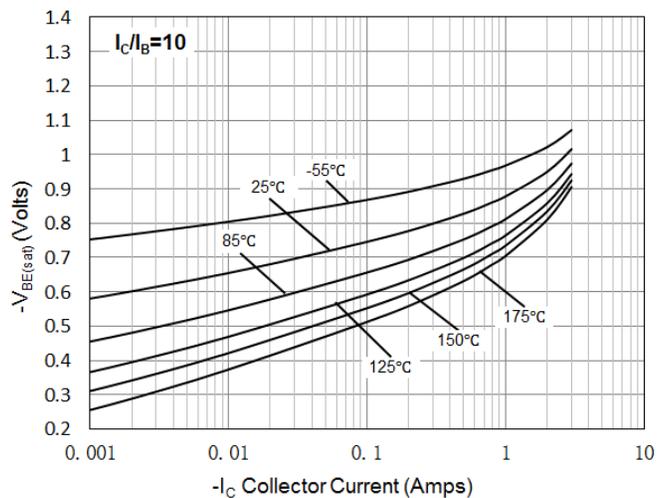
**$V_{CE(sat)}$  vs  $I_C$**



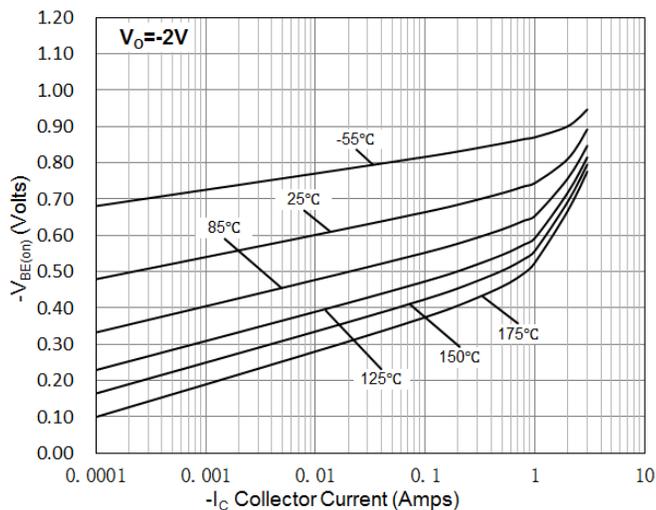
**$V_{CE(sat)}$  vs  $I_C$**



**$h_{FE}$  vs  $I_C$**



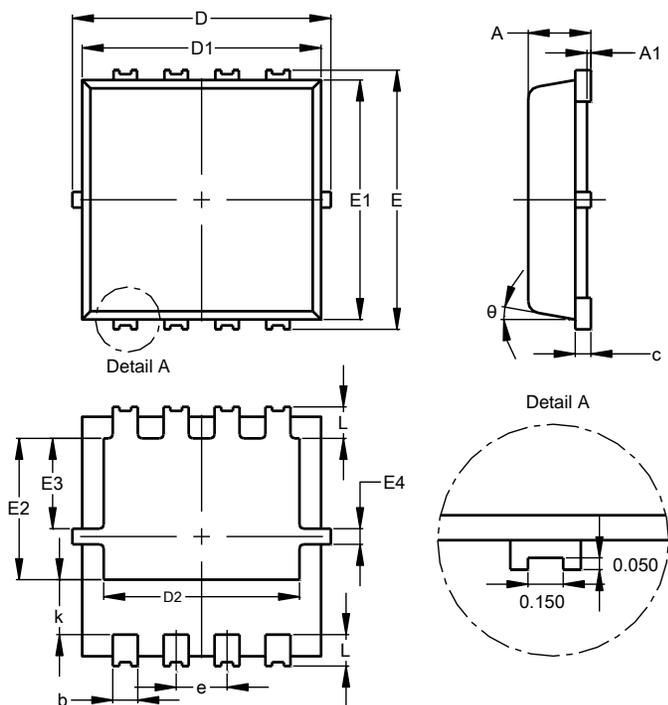
**$V_{BE(sat)}$  vs  $I_C$**



**$V_{BE(on)}$  vs  $I_C$**

### Package Outline Dimensions

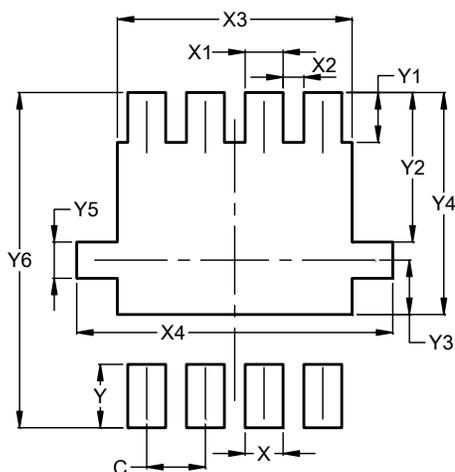
PowerDI3333-8 (SWP) (Type UX)



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Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	--
b	0.25	0.40	0.32
c	0.10	0.25	0.15
D	3.20	3.40	3.30
D1	2.95	3.15	3.05
D2	2.30	2.70	2.50
E	3.20	3.40	3.30
E1	2.95	3.15	3.05
E2	1.60	2.00	1.80
E3	0.95	1.35	1.15
E4	0.10	0.30	0.20
e	--	--	0.65
k	0.50	0.90	0.70
L	0.30	0.50	0.40
θ	0°	12°	10°
All Dimensions in mm			

### Suggested Pad Layout

PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.600
X4	3.500
Y	0.700
Y1	0.550
Y2	1.650
Y3	0.600
Y4	2.450
Y5	0.400
Y6	3.700